

Thermal Paste Series

Designed as an all-round thermal paste with the best possible price-performance ratio, as well as a high thermal conductivity, the EC360® EMERALD series is the ideal thermal paste for gaming PCs and sophisticated industrial cooling systems. A special compound, characterized by outstanding stability and an excellent thermal conductivity of 9 W/mK, make this thermal

paste one of the most effective thermal conductors. Its good consistency makes it easy to spread and install. Ideal for use with high-performance CPUs and GPUs. It is long-lasting: low bleed, non-flowing and low evaporation mean it will stay in place and not dry out over time. At the same time, it is not electrically conductive, which allows a safe application.

Types and Configurations

Type*	Available sizes*	
Tube	4 g, 20 g	

^{*} Custom configurations are available upon request, for worldwide industrial inquiries please contact us at: sales@extremecool360.com

Technical Properties

Properties	Unit	Value	Test method
Color	-	grey	Visual
Thermal Conductivity	W/mK	9.0	ROCT 8.140-82
Thermal Impedance	°C-in/W	0.14	ROCT 8.140-82
Specific Gravity	g / cm³	1.8	ASTM D 1475
Evaporation(200°C/24h)	%	0.001	FED STD 791
Bleed(200°C/24h)	%	0.07	FED STD 791
Dissipation Factor	100 Hz	0.005	ASTM D 150
Viscosity	cP	68	GB T-10247
Dielectric Constant	100 Hz	4.0	ASTM D 150
Usable Temperatures	°C	-55 - 220	EN 344

Installation Recommendation

- Clean surfaces from dirt and other possible residue. If applicable, isopropyl 90% alcohol is recommended to ensure a clean surface.
- Apply the product, for example by applying a drop in the center of the chip.
- Install the heatsink. Ideally the drop should have spread now, covering the entire chip in a thin layer of thermal paste without any air bubbles.
- If the result is not satisfactory apply again in a different quantity until the desired result has been achieved.